



Solder plus Support

# REL22™

## SOLDER ALLOY

Available in Paste, Wire and Bar



### REL22 ALLOY AT A GLANCE

- ▶ Exceptional durability for use in extremely harsh environments
- ▶ Reliability equal to Sn/Ag/Bi/Sb/Ni/Cu with wider process window
- ▶ Mitigates tin whisker growth
- ▶ Creep rates lower than SAC alloys
- ▶ High reliability/high strength
- ▶ Improved thermal cycling performance
- ▶ Improved wetting versus all low/no-silver alloys



AIM, a leading global manufacturer of solder assembly materials for the electronics industry, introduces REL22, a high reliability, high strength lead-free solder alloy.

**REL22 LEAD-FREE SOLDER ALLOY** developed by AIM, has been specifically engineered as an easily processed, exceptionally durable alloy for extreme service environments. The low creep rates exhibited by REL22 make it ideal for applications where thermal shock, vibration and high g-forces are experienced. REL22 also possesses a stable metallic grain structure after aging and low intermetallic growth on copper surfaces. Testing demonstrates that REL22 is well suited to extreme thermal exposure operating environments such as under-hood automotive, avionics/aerospace and other severe operating environments. Additionally, in extensive testing, REL22 has demonstrated a reduction in tin whisker formation making it the ideal alloy for all mission critical electronics applications. REL22 has also been developed to address production and quality issues common to similar alloys including Sn/Ag/Bi/Sb/Ni/Cu, such as pin-holes on SMT solder joints and voiding on BTC components.

#### REL22™ CAST COMPARISON

